Outline

IPCA Show 2015 (45th International Electronic Circuits Exhibition)

- ●Module Japan 2015
- ●EMS Japan 2015

Sponsored by: Japan Electronics Packaging and Circuits Association (JPCA) Special cooperation from: EMSOne (Tentative)

Large Electronics Show 2015

- ●PE PROCESS 2015
- Device Engineering 2015
- Solid-State Lighting 2015

Cosponsored by: Japan Electronics Packaging and Circuits Association(JPCA) and The Semiconductor Industry News (Sangyo Times Inc.)

WIRE Japan Show 2015 (Electric wire, Cable, and Connector Exhibition)

WIRE Japan Show Seminar

Cosponsored by: Japan Electronics Packaging and Circuits Association(JPCA) and THE ELECTRIC WIRE & CABLE NEWS(KOGYO TSUSHIN CO., LTD.)

2015 Microelectronics Show (29th Advanced Electronics Packaging Exhibition)

- Advanced Electronics Packaging (JISSO) Technology Symposium
- ●Academic Plaza
- ●eX-tech 2015

Sponsored by: Japan Institute of Electronics Packaging (JIEP)

JISSO PROTEC 2015 (16th Jisso Process Technology Exhibition)

Sponsored by: Japan Robot Association (JARA)

Entrance Fee JPY 1,000 (Tax included)

Free Adminssion for visitors with invitations and those who have pre-registered online.

Organizing Committee











Our objective is to contribute to the advancement of the electronic circuit industry and all related fields by presenting an exhibition of products, knowledge and solutions related to the electronic circuits and packaging technologies used in all electronic devices, IT devices and equipment, as well as the design, testing and logistics of large electronics (printed electronics, stretchable electronics, etc.)

Exhibition Period & Venue

Wednesday - Friday, June 3 - 5, 2015. 10:00 a.m. to 5:00 p.m. East Exhibition Hall and Conference Tower, Tokyo Big Sight (Tentative)

Ministry of Economy, Trade and Industry, Organization for Small & Medium Enterprises and Regional Innovation JAPAN Kanto Head Office (Tentative)

Special Cooperation

Camera and Imaging Products Association (CIPA)

Japan Embedded Systems Technology Association (JASA)

Japan Copper Development Association (JCDA) Nippon Electric Device Industry Association (NEDIA)

Electronic circuits ultra-high Efficiency System of Manufacturing for Agile Production (E-ESMAP) EMSOne (Tentative) SEMI Japan(Tentative)

Overseas Cooperation

World Electronic Circuits Council (WECC) Member Associates:

China Printed Circuit Association (CPCA)

European Institute of Printed Circuits (EIPC)

Hong Kong Printed Circuit Association (HKPCA)

IPC- Association Connecting Electronics Industries (IPC) Indian Printed Circuit Association (IPCA)

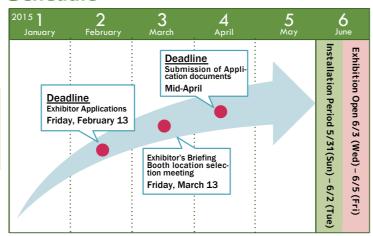
Korean Printed Circuit Association (KPCA)

Taiwan Printed Circuit Association (TPCA)

• Managed by

Japan Electronics Packaging and Circuits Association (JPCA)

Schedule



We are now looking for 2015 exhibition sponsors!

Want to become an exhibition sponsor?

attended by 120,000 Japanese and don't want to miss this opportunity! Exhibition sponsors will receive the benefits shown at right.

* Please contact the administrative office for more information.

Period	Late November to the end of the exhibition (held one after the other)					
Place	The organizer joint planning venue inside the Monotsukuri Fiesta, the public events hall, and the keynote address hall					
Costs	Platinum sponsor : JPY 500,000 (Tax not included) Gold sponsor : JPY 200,000 (Tax not included) Silver sponsor : JPY 100,000 (Tax not included) Bronze sponsor : JPY 50,000 (Tax not included)					
Benefits	Benefit levels	Platinum	Gold	Silver	Bronze	
	①Advertising in the JPCA Show 2015 guidebook Expo Navi (a 350,000 yen value as per last year's fee)	•				
	② Display your company's logo at the opening ceremony and inside the reception hall	•				
	③ Display your company's logo inside the keynote address hall	•				
	④120,000 JPCA emails Sponsor company names listed in an email newsletter sent out to 80,000 past exhibition visitors and 40,000 semiconductor industry newspaper	•	•			
	© Display your company's logo inside the event booth and create a space for displaying your company's pamphlets and literature (your company is responsible for panel creation costs)	•	•	•		
	⑥ Display your company's logo in open seminar PowerPoint presentations	•		•		
	①Display your company's logo on the exhibition's official website	•	•	•	•	

Applications/Inquiries Official Website www.jpcashow.com



Japan Electronics ${
m P}$ ackaging and ${
m C}$ ircuits ${
m A}$ ssociation. / Kairo Kaikan 2F, 3-12-2, Nishiogikita, Suginami-ku, Tokyo 167-0042 Phone: +81-3-5310-2020 / Fax: +81-3-5310-2021 (show@jpca.org)











 Advanced Electronics Packaging (JISSO) TechnologySymposium

Academic Plaza

The Meteoric Rise of Japanese Manufacturing!

Mount, Connect, Manufacture,

and Expand



IPCA 2015 Show

PUB Tech 2015 EMS JAPAN 2015

Module JAPAN 2015



Monotsukuri Fiesta 2015

Shaping the Dream Expo

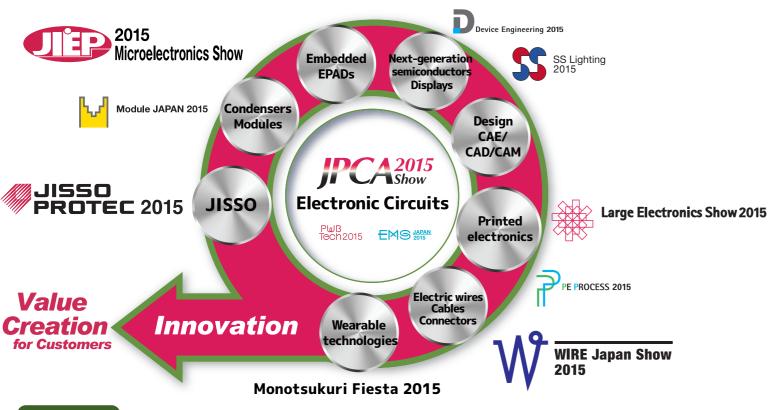
NEDIA Electronic Device Exhibition

- ●Embedded technology (JASA) special exhibition
- 3D-MID Pavilion (Tentative) ●The 20th Semiconductor of

The World's top-level, **Industry-Academia Collaboration**

The Total-Solution Exhibition for Electronic Equipment





Exhibition Theme

Mount, Connect, Manufacture, and Expand

Exhibition Feature

- Everyone in the electronic circuit industry participates.
- Comprehensive exhibition encompassing all products, technologies and services in electronic circuit production, development and research.
- •Users and buyers from Japan and overseas attend the exhibition with the aim of purchasing new products and adopting new technologies.
- Excellent for raising awareness, recognition and credibility of your company (product or technology) within the industry.
- A highly effective venue for the launch and marketing of new products and technologies.
- •As a comprehensive, specialized electronic circuit and packaging exhibition, the event will offer the perfect venue for exhibitors to form partnerships, conduct business and exchange information.

Exhibition Highlights

Large Electronics Show 2015

Since 2010, this specialized exhibition has been focusing on large electronics with relations to LED and printed electronics.

The 2015 exhibition will put a spotlight on condensers as one of Japan's vaunted electronic components, and will issue a grand call for corporate participation.

What Japan has to offer the world

Monotsukuri Fiesta 2015

- New sensor module pavilion for the age of M2M and trillion-sensors
- New local government organizer area
- New pavilions of research institutes and embassies in Japan, such as the Israel Embassy
- ●More—bitors expected in NEDIA Electronic Device Exhibition

WIRE Japan Show 2015

Held concurrently with the JPCA Show since 2014, the WIRE Japan Show is the only exhibition in Japan for wiring, cabling, connectors, and peripheral equip-

ment. This specialized exhibition spans a wide variety of products and technical fields, including the wiring and cabling, wire processors, wiring members, wire harness processors, and wire/cable measuring instruments which are keys to for industrial equipment, automobiles, and communications. 2015 will take exhibition scale up a notch.





Key business visitors categories (excerpt)

Car Electronics/Automotive parts

AUTOPROST, ASTI, JECS, KYB, Robert Bosch, SynPower, TDK, TLB Vehicle Registration Services, WOOJU I-TECH, AISAN INDUSTRY, aisin-aw, Aisin Seiki, Akebono Brake, ASMO, Alpine, ANDEN, ISUZU MOTOR, ICHIKOH, OMRON AUTOMOTIVE ELECTRONICS, CARMATE, CALSONICKANSEI, Kawasaki Heavy Industries, Kubota, KEIHIN, KOITO MANUFACTURING, Komatsu, Sankei Giken Kogyo, Jeco, SHOWA, SUZUKI MOTOR, STANLEY ELECTRIC, Sumitomo Wiring Systems, DENSO, TOKAIRIKA, Toyo Denso, TOYOTA INDUSTRIES, Toyota Motor, TOYOTA CENTRAL R&D LABS, TOYOTA TECHNICAL DEVELOPMENT, TOYOTA BOSHOKU, Transtron, Nagano Jeco, Nissan MOTOR, NISSAN MOTOR LIGHT TRUCK, NIPPON SOKEN, Nippon Seiki, NSK, NGK SPARK PLUG, NHK SPRING, Pioneer, Panasonic Automotive & Industrial Systems Company, BMW, Visteon, Hitachi Automotive Systems, Hino Motors, FALTEC, Fuji Heavy Industries, FUJITSU TEN, FURUKAWA ELECTRIC, Robert Bosch GmbH, Honda Cars YOKOHAMA, Honda Motor, Honda R&D, MAHLE, Mazda Motor, Mitsuba, Mitsubishi Motors, Mitsubishi Heavy Industries, Murakami Corporation, YAZAKI Corporation, Yamaha Motor, Empire Motor, OILES, DAIHATSU MOTOR, IHARA MANUFACTURING, Hino Engineering, KYOCERA, Mitsubishi Fuso Truck and Bus, Mitsubishi Materials, Mitsubishi Electric, Delphi Automotive, NIPPON MEKTRON, Fujikura, Honda Automobile R&D Center etc...

Aircraft / Aerospace IIHI, HIREC, NEC Network and Sensor, Panasonic Industrial Devices Materials (Suzhou), YAC Kokusai Dennetsu, HIWIN, Kyokko Ins, Kanto Aircraft, SUMITOMO PRECISION PROD-UCTS, Nakanihon Air Service, Nippon Avionics, Fuji Heavy Industries, JAXA, NEC TOSHIBA Space System, Kawasaki Heavy Industries, TOKYO AIRCRAFT, Panasonic, Hitachi, Nippon Avionics, Fujikura, Mitsubishi Heavy Industries, Mitsubishi Electric, Mitsubishi Electric TOKKI System, MEISEI ELECTRIC, Ryoei Technica etc...

OA / Industrial Equipment

CANON, TAIYO, TDK, CBC Optics, DongGuan SynPower, EIZO, HYUNDAI TECH, NEC Platforms, TDK-Lambda, OMRON, CASIO COMPUTER, Panasonic Factory Solutions, Panasonic Automotive & Industrial Systems Company, Aichi Tokei Denki, Oki Electric Industry, IHI scube, TAIYO HOLDINGS, Dai Nippon Printing, IWAKI, Nikon, ORIENTAL MOTOR, KEYENCE, CANON ELECTRON-ICS, CANON FINETECH, KYOCERA Document Solutions, Kubota, komatsu, GE FUJI METER, JANOME SEWING MACHINE, Sumitomo Heavy Industries, SEIKO EPSON, TOSHIBA, TOSHIBA TEC, TMEIC, NIDEC SANKYO, Hitachi, FANUC, Fuji Xerox, FUJITSU, FUJI ELECTRIC, Mitsubishi Electric, Mitsubishi Electric Engineering, Murata Manufacturing, YASKAWA ELECTRIC, Ricoh etc...

ACE TECH CIRCUIT, Adroit Circuit Logix Private Limited, AP TECH, ASIA INTEL COMMUNICATIONS, AU Optronics Corporation, Chang Sung Corporation, Chicony Power Technology, Chung-Nam national university, CviLux Corporation, Dynatron, EIZO, Elec&Eltek Company, EQUIS n ZAROO, Hanbit chemical, Hangzhou H3C Technologies, HOYA CANDEO OPTRONICS, HUAWEI, ILJUCorporation, Interflex, LG innotek, Optec Technology, Panduit Corporation, PFU TECHNOCONSUL, POONGWON, Shengyi Tech, Shenzhen Great Technologies, HoyA CANDEO OPTRONICS, HUAWEI, ILJUCorporation, Interflex, LG innotek, Optec Technology, Panduit Corporation, PFU TECHNOCONSUL, POONGWON, Shengyi Tech, Shenzhen Great Technologies, Sony Mobile Communications, TDK Panasonic Solution Technologies, Fujikura, Hitachi ICT Business Services, KYOCERA Crystal Device, Mitsubishi Electric Engineering, Sumitomo Electric Industries, SHOWA DENKO, Toshiba solutions, IBM Japan, NEC, PUJIT-SU, FUJITSU OPTICAL COMPONENTS, I-O DATA DEVICE, ICOM, Aiphone, hTC, NEC, NEC Platforms, NEC NETWORK PRODUCTS, NEC MAGNUS Communications, NTT ELECTRONICS, NTT DATA, NTT DOCOMO, LG Electronics, Oki Electric Industry, OMRON, OLYMPUS IMAGING, CASIO COMPUTER, Canon, CANON ELECTRONICS, KYOCERA, KYOCERA Document Solutions, KDDI, KONICA MINOLTA, NEC SAITAMA, SAXA Holdings, SAXA Techno, SAMSUNG ELECTRO-MECHANICS, JR Souken Information Systems, CITIZEN ELECTRONICS, Sharp, New Japan Radio, SEIKO EPSON, Sony, Sony, Sony, Business Solutions, Sony Mobile Communications, Hitachi BB, Dai Nippon Printing, DENSO WAVE, TOSHIBA, IBM Japan, NIPPON TELEGRAPH AND TELEPHONE, Japan Radio, Pioneer, Panasonic, Panasonic System Networks, Panasonic Mobile Communications, Hitachi Kokusai Electric, Hitachi, Hitachi ULSI Systems, FUJITSU, FUJITSU Advanced Technologies, FUJITSU LABORATORIES, FUJITSU CIT, FUJITSU TELECOM NETWORKS, Mitsubishi Electric, Yahoo Japan etc...

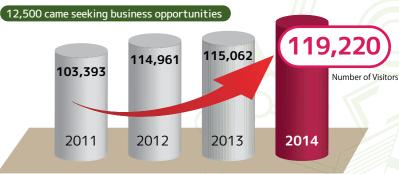
AV / Consumer Electronics ASTI, Avantpac Technology, BeLINK JAPAN, CJ TECH, dadny, EPE, FDK, HOYA, JINUTEC, KISCO, Lenovo, LFK, LG Display, LG Electronics, LG Electronics JAPAN, Luxshare-ICT, NEC Display Solutions, Samsung Electronics, Shanghai GeXinShiYe, SHENGYI TECHNOLOGY, SHENZHEN YASUDA INTERNATIONAL, Simplay Labs LLC, SMK, SSL lighting, TDK, Taiwan Nippor Kayaku, Taur Technology, Tempra Corporation, United Asia Technologies(HK), D.M.K, FSC, JVC KENWOOD, UACJ Foil, VSN, Aiphone, Aoi-electric, asahi-tushin, ASHIDA SOUND, ASTRODESIGN, AZDEN, ARS Alpine Electronics, ALPS ELECTRIC, IDEA SYSTEM, Interface, Autopsy imaging Information Center, A-R-Tec, SOC, Edison company, MYT, audio-technica, COWBELL ENGINEERING, KORG, THERMOS, Shimasei, Sony Computer Entertainment, D&M Holdings, Technica Fukui, DRETEC, Nikon Systems, Fujikura, VentureCraft, Yamari, UNION SEIMITSU, Lamp On, MARUWA CORPORATION, NORIMOTO MANUFACTURING TAKAMATSU Plating, SANNO, MURAMOTO Industory, tanakasangyo, TOSHIBA Corporation, TOWA ELECTRONICS, AU Optronics, MOJI Holdings, kyoritsu-e, KowaOpricalProducts, HIROSE ELECTRIC, Mitsubishi Electric Engineering, Mitsubishi Electric Home Appllance, Mitsubishi Electric Corporation, SANWA Denshi kiki, SANKO, DAIKIN, Sumitomo Electric, Towada Pioneer, KONISHIYASU, kkmt, MATSUMOTOSHO, Shin-Etsu Polymer, SHINKO ELECTRIC, INDUSTRIES, SHINSEI ELECTRONICS, New Japan Radio, Nishiyama Industry, SEIRYO-TECHNICA, FUNAI ELECTRIC, Dai Nippon Printing, Churvo engineering, Nagano Japan Radio, TOKAI, Shimoda Group, Tokyo Tan-Ichi, TOSHIBA Computer Technology, TOSHIBA DIGITAL MEDIA ENGINEERING, TOSHIBA MULTIMEDIA DEVICES, TOSHIBA LIFESTYLE PRODUCTS & SERVICE, TOSHIBA LOGISTICS, TOHOKU EPSON, TOPPAN PRINTING, NITTOH KOGAKU, NIPPON MEKTRON, NEC, Nidec Copal, Hitachi Appliances, Hitachi Maxell, HAKKO, FUJIFILM Imaging Systems, FUJIFILM Optics, FUJI KOGYO, HOKURIKU ELECTRIC INDUSTRY, Kitani Electric, OMRON, OLYMPUS, OLYMPUS IMAGING, ONKYO CORPORATION, CASIO COMPUTER, Canon, KYOCERA, Global Electronics Corporation, Ktech, "K" LINE LOGIS-TICS, KONICA MINOLTA, COHERENT JAPAN, SIIX Corporation, CITIZEN ELECTRONICS, STANLEY ELECTRIC, SEIKA Electronics, SEIKO NPC CORPORATION, Seiko Instruments, SEIKO EPSON, SENDAK CORPORA TION, Sony, Sony EMCS, Sony LSI Design, Sony Mobile Communications, TANASHIN DENKI, TEAC, TESCOM, DENSO INDUSTRY, TOSHIBA, TOSHIBA, CARRIER, TOSHIBA Lighting & Technology, TOTO, MICRONICS JAPAN, Haier Asia, Pioneer, Hagiwara Solutions, Panasonic, Panasonic Factory Solutions, Panasonic Production, AVC Networks Company, Panasonic Automotive & Industrial Systems Company, PS Tokki Hibino, Foster Electric, Fujipream, Minebea, RHYTHM KYOSHIN, Rohde & Schwarz Japan, OKAMOTO GLASS, Hisense Japan, AOF Japan, INFOCITY, enplas, MAGX, Sharp, SENDAI NIKON, TAIYO YUDEN, Hitachi, FUJITSU GENERAL. Fuiifilm. Mitsubishi Electric, MITSUMI ELECTRIC, Murata Manufacturing, YAMAHA, Ricoh, Wacom etc...

Medical / Instruments Atom Medical, Olympus, Olympus Medical Systems, KONOKO, Johnson & Johnson, Shirakawa Olympus, Sony, TANITA, TERUMO, Toshiba Medical Systems, TOPCON, NIKKISO, NIHON KOHDEN, Panasonic Healthcare, Hitachi, Hitachi Medical Corporation, Philips Electronics Japan, Fukuda Denshi, Rion atm International, CKD, EXTOL, Frost & Sullivan, GEHC Japan, Green Planets, MHR Technical Laboratory, NAN KAI CORPORATION, NLT technology, SEMITEC, SAMSUNG, Shanghai Meadville Science & Technology, TDK, ARKRAY, AIVISION, Agilent Technologies, Adamant, ADD-PLUS WEST JAPAN, Abbott Japan, Ushio, AR BROWN, Echo Electricity, Fandf, Olympus engineering, Career Development Associates, KONICA MINOLTA, SAKASE CHEMICAL, GSI Group Japan, Sharp, SCHOTT MORITEX, Star Product, step-science, Stella, TAKANO, TATSUTA ELECTRIC WIRE & CABLE, Techno Toppan Forms, TOITU, Nipro Medical Electronics Systems, Nipro, Panasonic, BeeBest, Hirose, Hirose

EMS Asia Electronics, Oki Electric Industry, Origin Electric, KAGA COMPONENTS, KAGA ELECTRONICS, SANSHIN Electric, SIIX, Shikino High-Tech, SHINSEI ELECTRONICS, SEIKO PRECISION, Celestica, TAKAYA, TOSSLEC, Tom Communication Industrial, Nagano Oki, NAKAYO, UMC ELECTRONICS, Yokogawa Solution Service, SANMINA, Jabil Japan, Flextronics International, FUJITSU, Katada Denki, DI-NIKKO ENGINEERING, Daimaru Kogyo, Toshiba Dee EMS, Tosa electronic, JVC Kenwood, PFU,PWB etc···

Electronic Circuit Board Eastern, Ibiden, NBC, Elna, Kyosha, Kyoden, KYOCERA Circuit Solutions, Samsung Electro-Mechanics Japan, Sanwa electronic circuit, Shira electronics industrial, SHIN-ASAHI ELECTRIC, Sumitomo Electric Printed Circuits, DAISHO DENSHI, Dai Nippon Printing, DENSO, Nitto Denko, CMK, NIPPON MEKTRON, Panasonic Automotive & Industrial Systems Company, Fujikura, Fujitsu Interconnect Technologies Meiko, Yamamoto Mfg, Shinko Electric Industries, Taiyo Yuden, TDK, Nippon Avionics, AT&S, C-Flex Electronics, Compeq Manfacturing, COMPEQ TECHNOLOGY HUIZHOU, DAEDUCK FLECTRONICS DAEDLICK GDS INNOFLEX Interflex ISU PETASYS KINSUSINTERCONNECT TECHNOLOGY, Korea Circuit, LG INNOEK, NAN YA PCB, NEWFLEX TECHNOLOGY, SAMSUNG ELECTRO-MECHANICS, SIMMTECH, Taiflex Scientific, UnimicronTechnology, YOUNG SHIN TECH, TRIPOD TECHNOLOGY CORPORATION, Career Technology (Mfg.), Unitech Printed Circuit Board Shennan Circuit Company, Shenzhen E-sun Electronics, Shenzhen Kehuilong Technology, Shenzhen Xinhansheng Technology, SHENZHEN JINZHOU PRECISION TECH-NOLOGY, Wuzhu Technology, Shenzhen Zhiboxin Circuit Board, Shenzhen Global Precision Circuits, Zefoc, Shenzhen Hongren Tongming Technology, Shenzhen Tianxi Science Development, SHENZHEN BOARDTECH, Shenzhen Newccess Industrial, Shenzhen Keva Electronic, ShenZhen XinDaHui Flex Cirtuit Technology, Guangdong Zhengye Technology, Dongguan Hetong Electronics, Chongqing KAIGE Electronics, SHENGYI TECHNOLOGY etc-

Around 120,000 visitors came in 2014



The 2014 show was attended by 3,000 overseas visitors, a number that continues to grow every year.

Our efforts to attract those in the electronic circuits industry will bring many visitors from overseas, particularly from China. Taiwan. Korea, and other Asian nations.

Scope of Exhibits

Possible to maximize appeal your products and technologies

Specialized Exhibitions

User-friendly exhibition to enable the matching of exhibitors and visitors

Half or more visitors are concerned with producing an electron, electric apparatuses, electronic circuit board production, and semiconductor parts production.

IPCA Show 2015

● PWB Tech 2015

Printed circuit boards, design process technology, circuit board materials, production process technology, materials and equipment, distribution and environmental systems, and related books, etc.

Module Japan 2015

 $Module\ substrate, module\ packaging, design, module\ substrate\ and\ packaging\ materials,\ \ {}^{HALL}$ production process technology, materials and equipment, distribution and environmental systems, and related books, etc.

■ EMS JAPAN 2015

Printed circuit board mounted substrate, module mounted substrate, all kinds of IC production, packaging, assembly, and inspection contract services, and related books, etc.

Large Electronics Show 2015

● PE Process Exhibition 2014

Printed electronics substrate, design and analysis systems, high function materials, HALL printing and coating equipment/systems, conveyor systems, drying, curing and sealing technologies, printed electronics applications, and related books, etc.

Device Engineering 2014

Electronic components, MEMS, all kinds of devices, design and analysis systems, all kinds of nano-materials, microprocessing equipment /systems, inspection and evaluation measuring technologies, all kinds of nano-technology applications, and related books,

Solid-State Lighting 2014

LED/OLED(organic EL) and applications manufacturing (lighting, energy, displays, touch panels, etc.), LED/OLED packaging materials, design and analysis systems, inspection and evaluation measuring technologies LED/OLED manufacturing, and related books, etc.

WIRE Japan Show 2015

● Electric wire, Cable, and Connector Exhibition

Industrial equipment and communications, such as electric wires, cables, connectors, electric wire processors, AWM, wire harness processors, and electric wire or cable measuring instrument, and related books, etc.

2015 Microelectronics Show

Implement advanced technologies, and Packaging Exhibition

Advanced Electronics Packaging(JISSO) TechnologySymposium

General high-density mounting technology of future advanced technologies, and Related

■ Academic Plaza ■ eX-tech 2015

JISSO PROTEC 2015

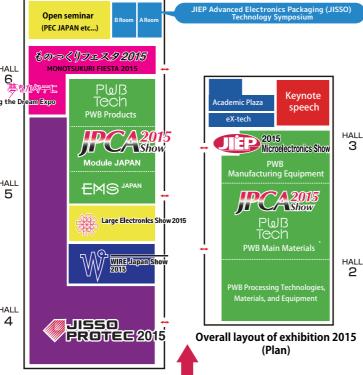
Implementation Process Technology Exhibition

Electronic component mounting apparatus, Related equipment and systems, Semiconductor packaging machines and systems, inspection and test equipment,

Monotsukuri Fiesta 2015

- Shaping the Dream Expo Supporting Exhibition for the Next Application
- NEDIA Electronic Device Exhibition
- 3D-MID Pavilion (Tentative)

"Which exhibition should I choose?" "Is this exhibition appropriate for our product? If you have any questions like above, please feel free to contact us



From the north concourse

Total Support for your Promotion

Display icons for functional technologies

Appeal your products and technologies easily to the applicat ion side (product designers, LSI product

高耐圧 情转技術 tal management and solitage technologies	(EMI/EMC) 対策技術 High-speck/high-frequency/ ine-frequency EMI/EMI/	3次元 PK 対策技術 ^{Design umbedded technolog}
薄型•軽量化 密度配線) 対策技術	省エネ・ 省資源 対策技術 Energy and rectinguistics	低コスト(I 対策技術

Project sign

can be displayed on this sign

2A - 10

能材料・プロセス技術・資

2A 通路 Aisle No.





Application icon

product and technology



Main applications of your company's

Superior DANTOTSU Your company's appealable technologies productivity icon

Exhibitors of material. facilities, equipment can display the "Supe-rior productivity" icon if the appeal is UP 30% productivity







Possible to held industry and academia cooperating and coordinating

Held numerous seminars program draws interest from highly motivated engineers

Various Seminars

• Previous listeners 12,316

more than 298 **●**Programs

6 Sessions 2,536 Participants **Keynote speech**

Experts in every world-leading industry will take the podium

There will also be panel discussions

PEC Japan 14 Sessions 650 Participants

Invite lecturers from all over the world

Advanced Electronics Packaging (JISSO) Technology Symposium

Interactive seminars on leading-edge technology Free tickets for exhibitors attract visitors!

Perennially popular open seminars

PRINTOBAN·JYUKU Seminar - easy to understand for arts students

Electronics Products BUNKAI Seminar – popular as standing audience appears every year **International Organizations Seminar** - catch world latest trends

And more than **250** seminars and events!

New Product Introduction seminar, JPCA Award

Well-equipped NPI venues are provided during the exhibition period for exhibitors to promote their new products and new technologies of the year to professionals and customers.

The organizers also will arrange JPCA A wards and publish a special news release on award winners to promote and publicize their products to increase exhibitor exposure, and improve their innovative image.

- Prepare special venue at the hall
- Free to join for exhibitors
- ●30 min per presentation
- Provide a closed room so that you can limit your listeners
- Attracted 1,342 listeners in 2013 (42 titles/3 days)
- Provide free equipment including laptop, projector, screen etc..
- ●Free join for JPCA Awards

Free Presentation for all exhibitors

Each company can arrange their promotion by utilizing

e.g.) Present introduction of your products during the seminar, and invite the audience to own booth for detailed explanation or individual consultation.

What's JPCA Award?

JPCA Award is a prize awarded for NPI presentation participants, which evaluated by the selection Committee organized by panels of experts. Award-winning companies will be introduced to media with press releases and to visitors by quide maps and literatures to promote their company's products and technology.



How to Apply

■Exhibition Booths

Standard booth size: 1 booth $9 \text{ m}(3\text{m}\times3\text{m})$

Non-Members JPY 410,000(Tax not included)/booth WECC Members JPY 350,000(Tax not included)/booth

**World Electronic Circuits Council (WECC) member associations are eligible for the JPCA member exhibitor's booth lease fees. WECC Member Associations: China Printed Circuit Association (CPCA), European Institute of Printed Circuits (EIPC), Hong Kong Printed Circuit Association (HKPCA), IPC – Association Connecting Electronics Industries (IPC), Indian Printed Circuit Association (IPCA), Korean Printed Circuit Association (KPCA), Taiwan Printed Circuit Association (TPCA).

■Corner Booth Fees

Exhibitors who would like to exhibit at a corner booth are requested to note this on the application form. You will receive priority to choose a corner booth at the time of selecting booth position.

Please be sure to apply early if you want a corner booth, as they are in limited supply. Corner charge: JPY15,000/booth (Tax not included) (charges will be doubled in case of two corner booths).

■Number of Booths that may be Applied for

There is no limit on the number of one booth units that exhibitors may apply for.

■How to Apply

Please select the exhibition you would like to exhibit at depending on the products, technologies, and services you would like to exhibit, and having carfully read the exhibition Regulations on the reverse side of the exhibition Application Form, enter your choice of exhibition in the Application Form and post it to the JPCA office.

■Applications to be sent to

Japan Electronics Packaging and Circuits Association

Kairo Kaikan 2F, 3-12-2, Nishiogikita, Suginami-ku, Tokyo 167-0042 Phone: +81-3-5310-2020 / Fax: +81-3-5310-2021 (show@jpca.org)

■ Application Deadlines

Friday, February 14, 2015 (final deadline)

■Payment Deadline

Friday, March 13, 2015(single payment only)

■ Determination of Booth Position

Determining booth position: The booth positions will be determined at the Exhibitors' Briefing (scheduled to be held on Friday, March 13, 2015).

1. As a rule, booths assigned as part of the same application and for the same exhibition will be positioned together taking into account booth number and type

and the functional zoning layout of the exhibition hall. Based on this, exhibitors will be offered a choice of booth position, with priority given to corner booth applicants on a first-come-first-served basis (earlier applicants will get priority over later applicants). All other booth positions will be determined by JPCA taking booth proximity to the entrance to the hall into account.

2. Priority of selection will be based on the date of application as reflected by the receipt number issued by the JPCA office with early applications given priority over later ones.

■Cancellations

If an exhibit is cancelled to suit the exhibitor's circumstances, cancellation charges (full or partial fees) shall apply as below.

Date of receipt of written notice of cancellation (by post, fax, or email)	Cancellation charges	
Applicants		
By Friday, February 13, 2015	50% of booth fees	
From Saturday, February 14, 2015 to Friday, March 13, 2015	70% of booth fees	
From Saturday, March 14, 2015 onward	100% of booth fees	

Sponsored Seminars

This is a program perfectly suited to scheduled exhibitors who are looking to get new customers or gauge customer reaction.

The venue will be set up inside the exhibition hall. Closed presentation areas will also be created using partitions.

[Seminar Details]

- Location: Inside the exhibition hall (closed, walled in/roofless)
- Capacity: about 50 (auditorium-style)
- 1 set/stage: 45 mins
- Access fee: 820,000 yen (Tax not included)
- Application period start: March 16 (tentative)

This seminar allows each company to apply for up to 3 sets. All you will need to bring on the day of your presentation is your laptop. All other equipment (projector, screen, microphone, etc.) will be provided by exhibition staff. Please note that presentation timetables will be set by the administrative office in coordination with other participants on a first-come first-served basis.

Guide to Applications to Exhibit at Academic Plaza

An "Academic Plaza" event sponsored by JIEP with the aim of enhancing industry-academia collaboration will be held concurrently with JPCA Show 2015, Large Electronics Show 2015, WIRE Japan Show2015,2015 Microelectronics Show, and JISSO PROTEC 2015.

The latest research activities at universities, research institutes, and other related organizations, as well as research results will be presented through booth exhibitions and presentations, contributing to industry-academia collaboration, generation of new business opportunities, and encouraging joint research and development with companies. We urge persons from universities, research institutes and other related organizations to take advantage of this opportunity and further promote industry-academia collaboration.

Target Products and Technologies	All packaging and electronic technologies (materials technologies, circuit and packaging design technologies, high-speed and highfrequency technologies, electromagnetic property technologies, reliability analysis technologies, electronic parts and packaging technologies, optical circuit packaging technologies, environmentally friendly packaging technologies, semiconductor packaging technologies, micro-mechatronics packaging technology, etc.)		
Applications Expected From	Japanese and foreign universities, research institutes, related organizations (we request that you respond to questions from visitors to the extent possible during the exhibition period)		
Exhibitions	Exhibition and oral presentation of research results There are three formats for which you can apply: (1) Present on research results and introduce your laboratory (2) Only present research results (3) Only introduce your laboratory In the case of (1) and (3), each exhibitor (university, research institute, etc.) will be provided with one small room for their exhibition. Please contact the JIEP administrative office if two or more rooms are required.		
How to Apply	Interested exhibitors should contact the JIEP Office. TEL: +81-3-5310-2010 Email: academic@jiep.or.jp		

Basic Services (Free)

- **■** JPCA mail delivery service
- Distributing press releases
- Information posted on the official website
- Creating and distributing posters
- NPI Presentation Program
- Invitation to the Advanced Electronics Packaging (JISSO) Technology Symposium
- Providing brochures with an enclosed list of exhibitors (containing invitations) to lure visitors and VIP visitors
- Use of business discussion rooms at exhibition venue
- Information published in EXPO NAVI

We offer various types of support services to exhibitors to help them get the maximum results from the exhibition.

Exhibitor Support Program



Exhibitor Seminar

+

Press Support









Business Discussion Rooms for Rent

nars with small numbers of special clients.

Rental business discussion rooms are available for the purpose

of conducting business discussions, meetings and private semi-



Optional Support Services (Paid services)

Multipurpose Room/Stockroom

¥75,000

9 m²

1 light

1.3Kw

2 stands

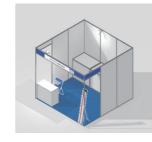
We will make arrangements for private stockrooms at the exhibition venue that can be locked up.

Signboard Advertisement

You can put up advertisements on the various types of signboards set up in the exhibition venue. Please make use of this as a public relations service to attract visitors to your exhibition booth.

Information on the standard package booth for exhibitors

We are offering various types of low-cost package booths where all it takes to be able to exhibit is to bring in the exhibits, product samples, presentation panels and catalogs/brochures to the venue on the day an hour before the exhibition opens. *Specifications and prices are subject to change. *See official website for more details.



1 booth / 1 side open plan

Company name display

Parapets

Lighting 40W

100W spotlights

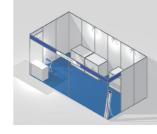
Power outlet 100

Electrical wiring

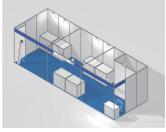
Reception set

Display stands

Catalog stand



2 booths / 1 side open plan	¥ 118,000
Specifications	Number
Parapets	1
Carpet	18 m
Company name display	1
Lighting 40W	2light
100W spotlights	4
Power outlet 100V	1
Electrical wiring	1.6Kw
Reception set	1
Display stands	4 stands
Catalog stand	1



¥ 170,000
Number
1
27 m
1
3light
6
1
1.9Kw
1
6 stands
1



4 booths / 3 sides open plan	¥ 213,000 Number	
Specifications		
Parapets	1	
Carpet	36 m²	
Company name display	1	
Lighting 40W	4light	
100W spotlights	8	
Power outlet 100V	1	
Electrical wiring	2.2Kw	
Reception set	1	
Display stands	8 stands	
Catalog stand	1	

Prices are not inclusive of taxes